

SOT1307-1

plastic very thin fine-pitch ball grid array package; 64 balls;

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VF64A64
Package type industry code	VF64A64
Package style descriptive code	VF64A (very thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	16-6-2011

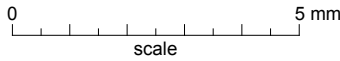
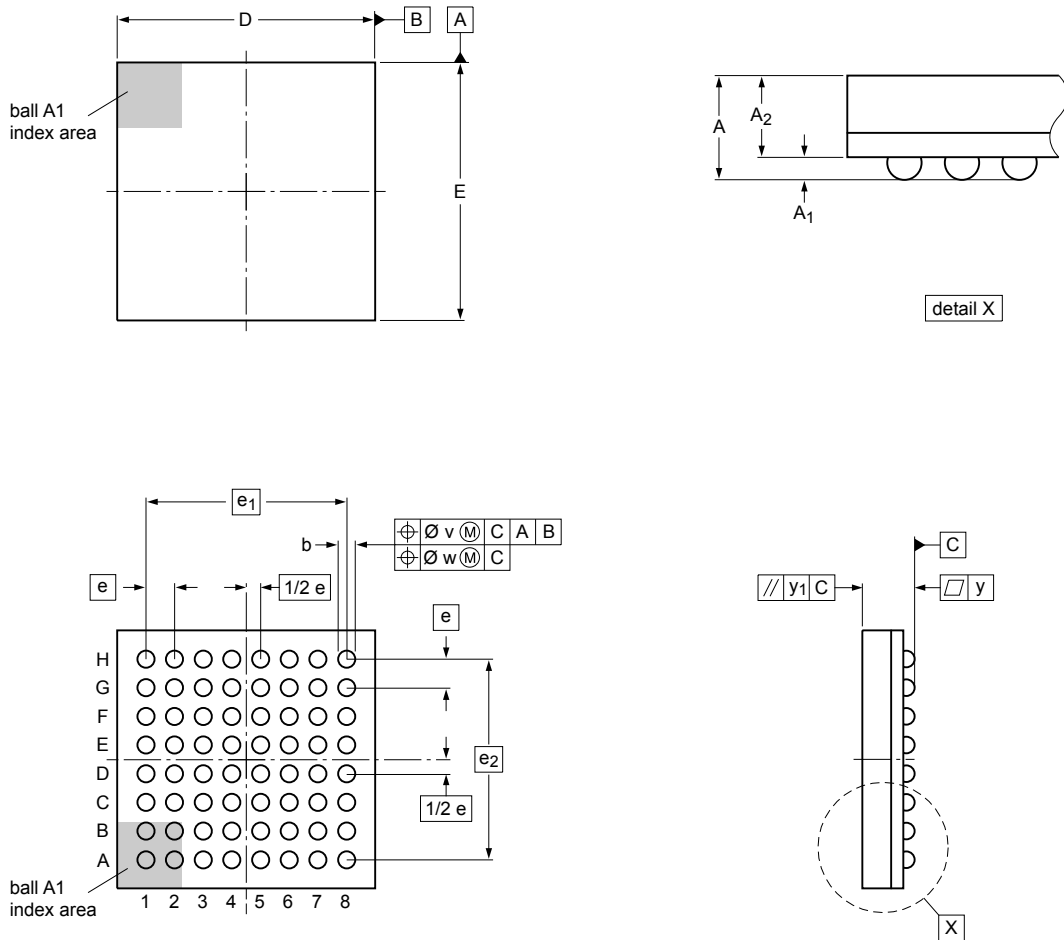
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.5	4.6	mm
E	package width	4.4	-	4.5	4.6	mm
A	seated height	0.8	-	0.9	1	mm
A ₂	package height	0.65	-	0.7	0.75	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	64	-	



2. Package outline

VFBGA64: plastic very thin fine-pitch ball grid array package; 64 balls; SOT1307-1



Dimensions

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
max	1.00	0.25	0.75	0.35	4.60	4.60							
mm nom	0.90	0.20	0.70	0.30	4.50	4.50	0.50	3.50	3.50	0.15	0.05	0.08	0.10
min	0.80	0.15	0.65	0.25	4.40	4.40							

sot1307-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1307-1					-11-06-14- 11-06-16

Fig. 1. Package outline VFBGA64 (SOT1307-1)

3. Legal information

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